

PLEASE CHECK WWW.MOLEX.COM FOR LATEST PART INFORMATION

Part Number: [5015681207](#)
Status: **Active**
Overview: [picoclasp](#)
Description: 1.00mm (.039") Pitch Pico-Clasp™ Wire-to-Board Header, Surface Mount, Single Row, Right Angle, with Positive Lock, 12 Circuits, Lead-free

Documents:
[3D Model](#)
[Drawing \(PDF\)](#)

[Product Specification PS-501568-001 \(PDF\)](#)
[RoHS Certificate of Compliance \(PDF\)](#)

General

Product Family	PCB Headers
Series	501568
Application	Wire-to-Board
Overview	picoclasp
Product Name	Pico-Clasp™

Physical

Breakaway	No
Circuits (Loaded)	12
Color - Resin	Natural
Durability (mating cycles max)	30
Glow-Wire Compliant	No
Lock to Mating Part	Yes
Material - Metal	Brass, Phosphor Bronze
Material - Plating Mating	Tin
Material - Plating Termination	Tin
Material - Resin	Nylon
Number of Rows	1
Orientation	Right Angle
PCB Locator	No
PCB Retention	Yes
Packaging Type	Embossed Tape on Reel
Pitch - Mating Interface (in)	0.039 In
Pitch - Mating Interface (mm)	1.00 mm
Polarized to Mating Part	Yes
Polarized to PCB	No
Stackable	No
Temperature Range - Operating	-40°C to +85°C
Termination Interface: Style	Surface Mount

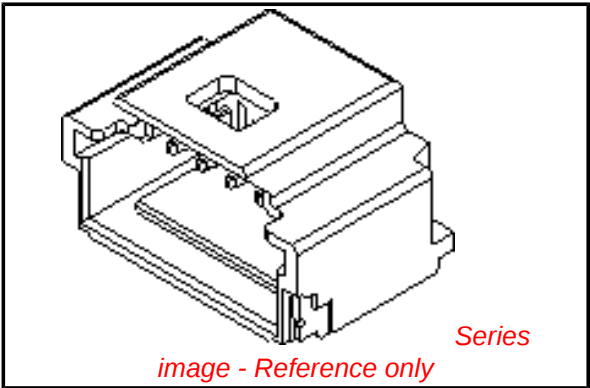
Electrical

Current - Maximum per Contact	1A
Voltage - Maximum	50V AC (RMS)/DC

Material Info

Reference - Drawing Numbers

Packaging Specification	SPK-501568-001
Product Specification	PS-501568-001, RPS-501331-001, RPS-501568-001, RPS-501568-002, RPS-501568-003, RPS-501568-004, RPS-501568-005, RPS-501940-001, RPS-501940-002
Sales Drawing	SD-501568-002, SD-501568-006



EU RoHS
ELV and RoHS
Compliant
REACH SVHC
Not Reviewed
Halogen-Free
Status
Not Reviewed



Need more information on product environmental compliance?

Email productcompliance@molex.com
For a multiple part number RoHS Certificate of Compliance, [click here](#)

Please visit the [Contact Us](#) section for any non-product compliance questions.

Search Parts in this Series
[501568Series](#)

Mates With
[501330](#) Pico-Clasp™ Wire-to-Board Female Housing

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F

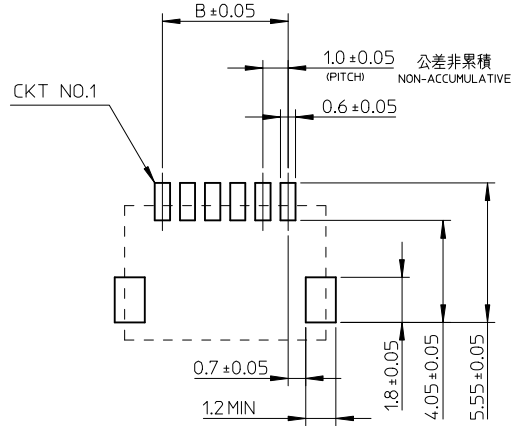
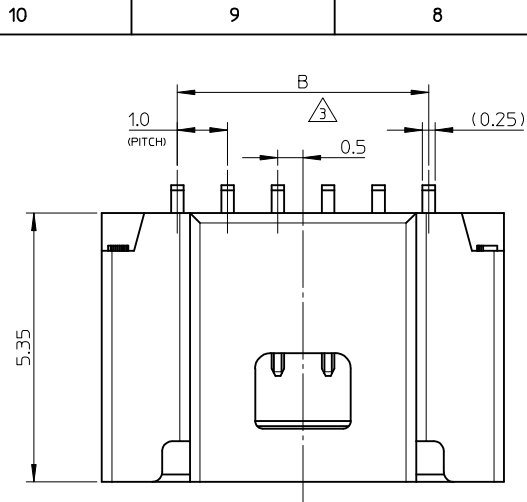
E

D

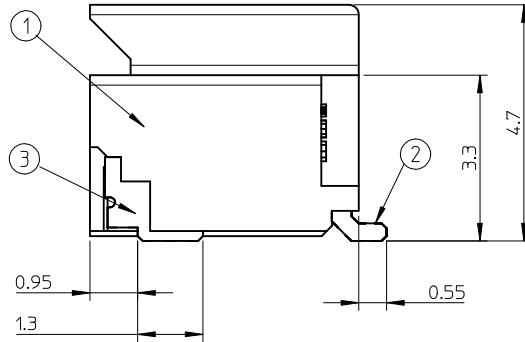
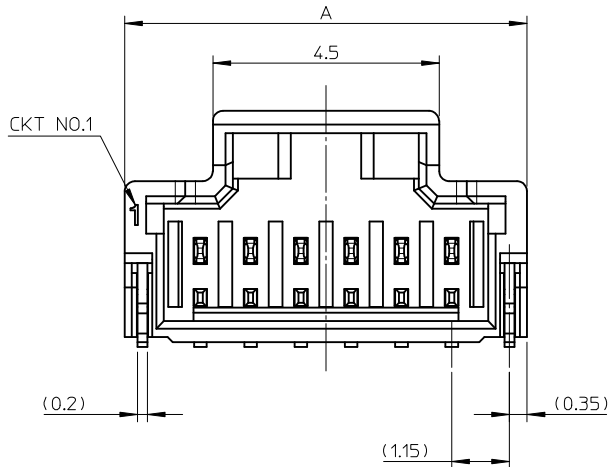
C

B

A



参考パターンレイアウト
RECOMMENDED PATTERN DIM.(REF)
SCALE:5-1



番号 NO.	部品 PART	材質 MATERIAL
①	ウェハー WAFER	耐熱ナイロン、UL94V-0 HEAT RESISTANCE NYLON, UL94V-0
②	ソルダーピン SOLDER PIN	りん青銅 PHOSPHOR BRONZE すずメッキ : 1 MICRO METER MINIMUM. TIN PLATING ニッケル下地メッキ : 1 MICRO METER MINIMUM. NICKEL UNDER PLATING
③	ネイル NAIL	黄銅 BRASS すずメッキ : 1 MICRO METER MINIMUM. TIN PLATING ニッケル下地メッキ : 1 MICRO METER MINIMUM. NICKEL UNDER PLATING

14.0	17.0	15
13.0	16.0	14
12.0	15.0	13
11.0	14.0	12
10.0	13.0	11
9.0	12.0	10
8.0	11.0	9
7.0	10.0	8
6.0	9.0	7
5.0	8.0	6
B	A	極数 CIRCUITS

NOTES

- かん相手 : 501330-****
MATE WITH : 501330-****
- ソルダーピン及びネイルの平坦度は0.1MAX.
SOLDER PIN AND NAIL COPLANARITY TO BE 0.1MAX.
- 極数 = 偶数に適用
APPLY FOR CKT SIZE=EVEN
- 2~5極は、SD-501568-001を参照下さい。
REFER TO SD-501568-001 ABOUT 2-5CKT.
- ELV AND RoHS COMPLIANT.

CONNECTOR SERIES No. 501568-***9

REVISED	EC NO: J2010-0339 DRWN: INAKAGAWA01 2009/09/01 CH'KD: MATSUMOTO 2009/09/01 APPR: HIRATA 2009/09/01	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE		SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION	
					MM ONLY		10:1	METRIC		
			10 UNDER	± 0.2	DRAWN BY	DATE	TITLE	1.0 WIRE TO BOARD CONN. 1-ROW R/A WAFER ASSY 6-15CKT		
			10 OVER 30 UNDER	± 0.25	CHECKED BY	DATE				
			30 OVER	± 0.3	MYAGI	2005/01/19	MOLEX INCORPORATED			
			ANGULAR ±3 °	APPROVED BY	DATE					
			DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	ANODA	2005/01/19	DOCUMENT NO.	SHEET NO.			
				SEE SHEET 2		SD-501568-002	1 OF 2			
		REV	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION							

	10	9	8	7	6	5	4	3	2	1	
F											F
E											E
D											D
C											C
B											B
A											A
	10	9	8	7	6	5	4	3	2	1	

紫 PA46 VIOLET	橙 PA46 ORANGE	茶 PA46 BROWN	緑 PA46 GREEN	色 COLOR
501568-1597	501568-1587	501568-1577	501568-1567	15
501568-1497	501568-1487	501568-1477	501568-1467	14
501568-1397	501568-1387	501568-1377	501568-1367	13
501568-1297	501568-1287	501568-1277	501568-1267	12
501568-1197	501568-1187	501568-1177	501568-1167	11
501568-1097	501568-1087	501568-1077	501568-1067	10
501568-0997	501568-0987	501568-0977	501568-0967	9
501568-0897	501568-0887	501568-0877	501568-0867	8
501568-0797	501568-0787	501568-0777	501568-0767	7
501568-0697	501568-0687	501568-0677	501568-0667	6
EMBOSSSED PACKAGE	EMBOSSSED PACKAGE	EMBOSSSED PACKAGE	EMBOSSSED PACKAGE	極数
オーダー番号 ORDER NO.	オーダー番号 ORDER NO.	オーダー番号 ORDER NO.	オーダー番号 ORDER NO.	CIRCUITS

CONNECTOR SERIES No. 501568-***9

青 PA46 BLUE	黄 PA46 YELLOW	赤 PA46 RED	黒 PA46 BLACK	自然色 PA6T NATURAL	色 COLOR
501568-1547	501568-1537	501568-1527		501568-1507	15
501568-1447	501568-1437	501568-1427		501568-1407	14
501568-1347	501568-1337	501568-1327		501568-1307	13
501568-1247	501568-1237	501568-1227		501568-1207	12
501568-1147	501568-1137	501568-1127		501568-1107	11
501568-1047	501568-1037	501568-1027		501568-1007	10
501568-0947	501568-0937	501568-0927	501568-0917	501568-0907	9
501568-0847	501568-0837	501568-0827	501568-0817	501568-0807	8
501568-0747	501568-0737	501568-0727		501568-0707	7
501568-0647	501568-0637	501568-0627	501568-0617	501568-0607	6
EMBOSSSED PACKAGE	EMBOSSSED PACKAGE	EMBOSSSED PACKAGE	EMBOSSSED PACKAGE	EMBOSSSED PACKAGE	極数
オーダー番号 ORDER NO.	オーダー番号 ORDER NO.	オーダー番号 ORDER NO.	オーダー番号 ORDER NO.	オーダー番号 ORDER NO.	CIRCUITS

CONNECTOR SERIES No. 501568-***9

REVISED

EC NO: J2010-0339

DRWN:TNAKAGAMA01 2009/09/01

CHKD:HMATSUMOTO 2009/09/01

APPR:HHIRATA 2009/09/01

DESCRIPTION

REV

GENERAL TOLERANCES
(UNLESS SPECIFIED)

10 UNDER

10 OVER 30 UNDER

30 OVER

ANGULAR

±0.2

±0.25

±0.3

±3

DRAFT WHERE APPLICABLE
MUST REMAIN
WITHIN DIMENSIONS

DIMENSION STYLE
MM ONLY

DRAWN BY DATE

CHECKED BY DATE

APPROVED BY DATE

MATERIAL NO.

1:1

SCALE

DESIGN UNITS
METRIC

THIRD ANGLE
PROJECTION

1.0 WIRE TO BOARD CONN.
1-ROW R/A WAFER ASSY
6-15CKT

MOLEX INCORPORATED

SD-501568-002

SHEET NO.
2 OF 2

SIZE
A3

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Rev. E 2006/04/15

9

8

7

6

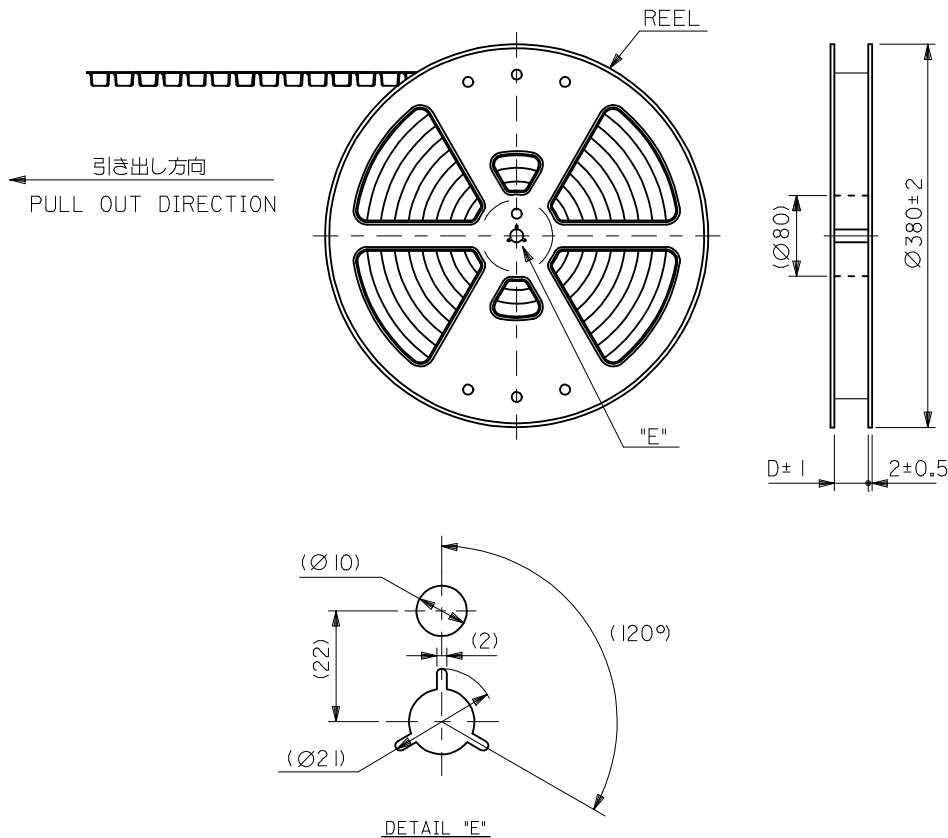
5

4

3

2

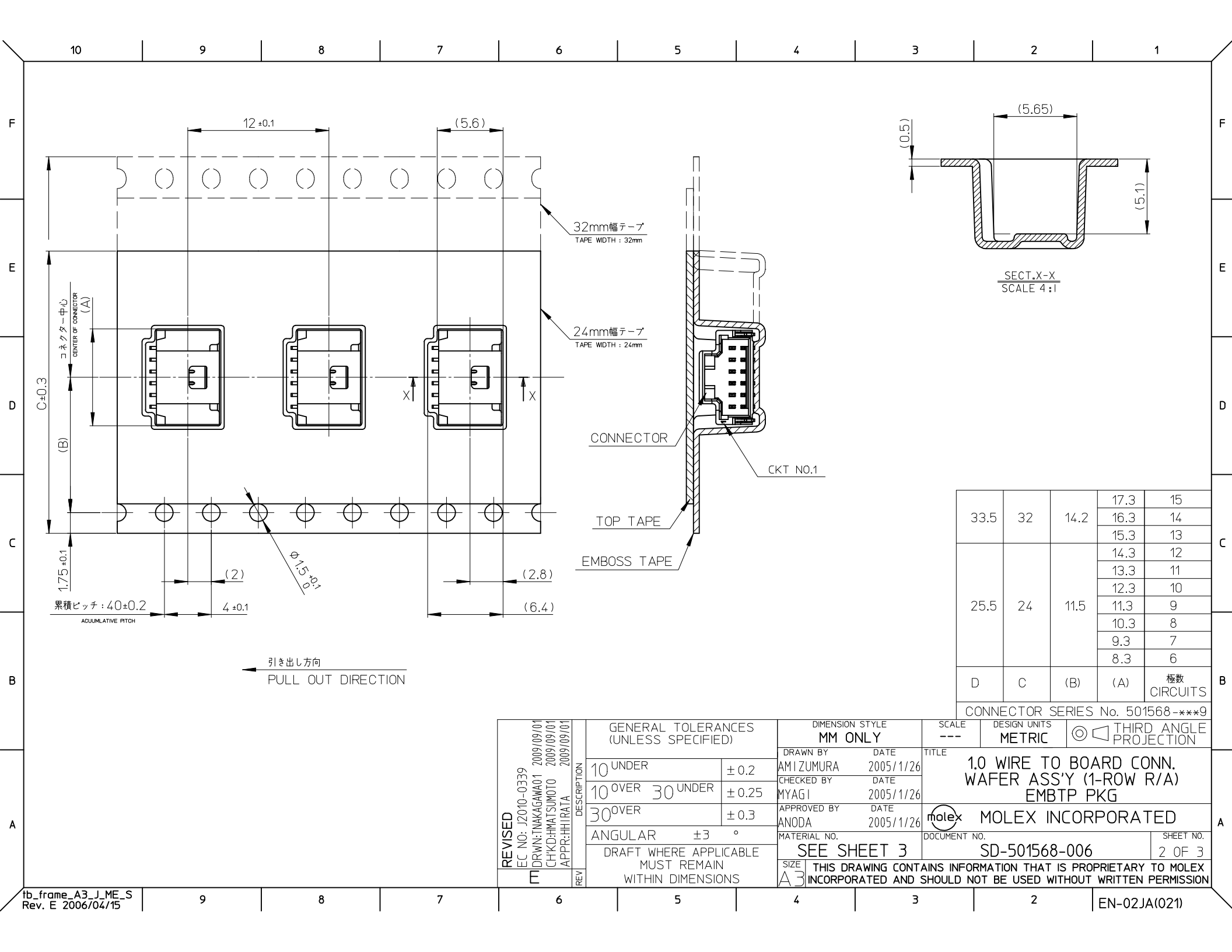
EN-02DA(021)



NOTES

1. 製品詳細寸法は製品単体図面を参照して下さい。
FOR DETAIL OF CONNECTOR DIMENSIONS, PLEASE SEE THE DRAWING OF CONNECTOR ITSELF (NOT PACKAGED).
2. 梱包数量 : 1300 個/リール
NUMBER OF CONNECTORS : 1300PIECES/REEL
3. リードテープ長さ
LEAD TAPE LENGTH
-
- The diagram illustrates the lead tape length. It shows a horizontal line representing the tape. A dimension line at the bottom indicates a total length of 400MIN. The tape is divided into three sections: a left section, a middle section labeled 'TOP TAPE BONDED PART (EMPTY)' with a length of '20 PIECES. MIN.', and a right section labeled '末端部 (空部) TAIL PART (EMPTY) 160MIN.'. A break symbol (two wavy lines) is shown in the middle section. Below the middle section, the text '部品挿入部 COMPONENT SUPPLIER' is written. A vertical dimension line on the right indicates the 160MIN. tail length.
4. 材料
MATERIAL
キャリアテープ: ポリプロピレン
CARRIER TAPE: POLYPROPYLENE
トップテープ: PET, PE, REF
TOP TAPE
リール: ポリスチレン (リサイクル材を含む)
REEL : POLYSTYRENE (RECYCLE MATERIAL CONTAINED)
5. ELV AND RoHS COMPLIANT.
6. ハイバリア梱包 (シリカゲル入り) 対応品である。(501568-**07 除く)
THIS PRODUCT IS HIGH BARRIER PACKAGE.(WITH SILICAGEL)
(BESIDES 501568-**07)
7. 開梱後の保管条件に注意のこと。(ハイバリア品対象: PS-501568-001 参照)
REFER TO PS-501568-001(HIGH BARRIER PRODUCT)
FOR CONDITIONS AFTER OPEN.

REVISED	EC NO.: J2010-0339 DRAWN: INAKAGAWA01 2009/09/01 CHKD: MATSUMOTO 2009/09/01 APPR: HIRATA 2009/09/01	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
			10 UNDER	± 0.2	DRAWN BY AMIZUMURA	DATE 2005/1/26	TITLE 1.0 WIRE TO BOARD CONN. WAFER ASS'Y (1-ROW R/A) EMBTP PKG			
			10 OVER 30 UNDER	± 0.25	CHECKED BY MYAGI	DATE 2005/1/26				
			30 OVER	± 0.3	APPROVED BY ANODA	DATE 2005/1/26				
			ANGULAR ±1 °		MATERIAL NO.		DOCUMENT NO.		SHEET NO.	
			DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE SHEET 3		SD-501568-006		1 OF 3	
REV			THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION							



33.5	32	14.2	17.3	15
			16.3	14
			15.3	13
			14.3	12
			13.3	11
			12.3	10
25.5	24	11.5	11.3	9
			10.3	8
			9.3	7
			8.3	6
D	C	(B)	(A)	極数 CIRCUITS

CONNECTOR SERIES No. 501568-***9

REVISED EC NO: J2010-0339 DRWN: TNAKAGAWA 2009/09/01 CHKD: MATSUMOTO 2009/09/01 APPR: HIRATA 2009/09/01	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		10 UNDER	± 0.2	DRAWN BY AMIZUMURA	DATE 2005/1/26	TITLE 1.0 WIRE TO BOARD CONN. WAFER ASS'Y (1-ROW R/A) EMBTP PKG				
		10 OVER 30 UNDER	± 0.25	CHECKED BY MYAGI	DATE 2005/1/26					
		30 OVER	± 0.3	APPROVED BY ANODA	DATE 2005/1/26	MOLEX INCORPORATED				
		ANGULAR ±3 °		MATERIAL NO.						
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE SHEET 3		SD-501568-006		2 OF 3		
	REV			SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				

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